## MOTOROLA SEMICONDUCTOR TECHNICAL DATA

# MC6802

# Microprocessor With Clock and Optional RAM

The MC6802 is a monolithic 8-bit microprocessor that contains all the registers and accumulators of the present MC6800 plus an internal clock oscillator and driver on the same chip. In addition, the MC6802 has 128 bytes of on-board RAM located at hex addresses \$0000 to \$007F. The first 32 bytes of RAM, at hex addresses \$0000 to \$001F, may be retained in a low power mode by utilizing V<sub>CC</sub> standby; thus, facilitating memory retention during a power-down situation.

The MC6802 is completely software compatible with the MC6800 as well as the entire M6800 family of parts. Hence, the MC6802 is expandable to 64K words.

- On-Chip Clock Circuit
- 128×8 Bit On-Chip RAM
- 32 Bytes of RAM are Retainable
- Software-Compatible with the MC6800
- Expandable to 64K Words
- Standard TTL-Compatible Inputs and Outputs
- 8-Bit Word Size
- 16-Bit Memory Addressing
- Interrupt Capability

## TYPICAL MICROCOMPUTER



This block diagram shows a typical cost effective microcomputer. The MPU is the center of the microcomputer system and is shown in a minimum system interfacing with a ROM combination chip. It is not intended that this system be limited to this function but that it be expandable with other parts in the M6800 Microcomputer family.

This document contains information on a new product. Specifications and information herein are subject to change without notice.

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#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	Vcc	-0.3 to +7.0	V
Input Voltage	Vin	-0.3 to +7.0	V
Operating Temperature Range MC6802, MC680A02, MC680B02 MC6802C, MC680A02C	TA	0 to +70 -40 to +85	°C
Storage Temperature Range	T <sub>stg</sub>	- 55 to + 150	°C

This input contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either VSS or VCC).

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Average Thermal Resistance (Junction to Ambient)			
Plastic	θJA	100	°C/W

#### POWER CONSIDERATIONS

The average chip-junction temperature, T<sub>J</sub>, in °C can be obtained from:  $T_J = T_A + (P_D \theta_{JA})$ 

where:

- = Ambient Temperature, °C TΑ
- = Package Thermal Resistance, Junction-to-Ambient, °C/W θJA
- ΡD
- PINT
- = PINT + PPORT = I<sub>CC</sub> × V<sub>CC</sub>, Watts Chip Internal Power = Port Power Dissipation, Watts User Determined PPORT

For most applications PPORT <PINT and can be neglected. PPORT may become significant if the device is configured to drive Darlington bases or sink LED loads.

An approximate relationship between P<sub>D</sub> and T<sub>J</sub> (if P<sub>PORT</sub> is neglected) is:  $P_D = K \div (T_J + 273^{\circ}C)$ 

Solving equations (1) and (2) for K gives:

$$T = P_{D} * (T_{A} + 273^{\circ}C) + \theta + A \cdot P_{D}^{2}$$
 (3)

 $K = P_{D} \cdot (T_{A} + 273^{\circ}C) + \theta_{JA} \cdot P_{D}^{2}$ (3) where K is a constant pertaining to the particular part. K can be determined from equation (3) by measuring P<sub>D</sub> (at equilibrium) for a known  $T_A$ . Using this value of K, the values of  $P_D$  and  $T_J$  can be obtained by solving equations (1) and (2) iteratively for any value of TA.

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(1)

(2)

Characteristic		Symbol	Min	Тур	Max	Unit
Input High Voltage	Logic, <u>EXTAL</u> RESET	VIH	V <sub>SS</sub> +2.0 V <sub>SS</sub> +4.0	_	V <sub>CC</sub> V <sub>CC</sub>	v
Input Low Voltage	ogic, EXTAL, RESET	VIL	V <sub>SS</sub> -0.3	_	V <sub>SS</sub> +0.8	٧
Input Leakage Current (Vin = 0 to 5.25 V, VDD = ma	x) Logic	lin	-	1.0	2.5	μA
Output High Voltage (I <sub>Load</sub> = -205 μA, V <sub>CC</sub> = min) (I <sub>Load</sub> = -145 μA, V <sub>CC</sub> = min) (I <sub>Load</sub> = -100 μA, V <sub>CC</sub> = min)	D0-D7 A0-A15, R/W, VMA, E BA	∨он	V <sub>SS</sub> +2.4 V <sub>SS</sub> +2.4 V <sub>SS</sub> +2.4	Ξ		v
Output Low Voltage (ILoad = 1.6 mA, V <sub>CC</sub> = min)		VOI	—		Vss+0.4	V
Internal Power Dissipation (Measured at $T_A = 0^{\circ}C$ )		PINT	—	0.750	1.0	• <b>W</b>
V <sub>DD</sub> Standby	Power Down Power Up	V <sub>SBB</sub> V <sub>SB</sub>	4.0 4.75	_	5.25 5.25	v
Standby Current		ISBB	-	_	8.0	mA
Capacitance # (V <sub>in</sub> =0, T <sub>A</sub> =25°C, f=1.0 MHz)	D0-D7 Logic Inputs <u>, EXTAL</u> A0-A15, R/W, VMA	C <sub>in</sub> C <sub>out</sub>	=	10 6.5	12.5 10 12	pF

## DC ELECTRICAL CHARACTERISTICS ( $V_{DD} = +5.0 \text{ Vdc} \pm 0.5\%$ , $V_{SS} = 0$ , $T_A = 0$ to 70°C, unless otherwise noted)

\*In power-down mode, maximum power dissipation is less than 42 mW. #Capacitances are periodically sampled rather than 100% tested.

## $\label{eq:control_times} \textbf{CONTROL TIMING} \quad (V_{CC} = 5.0 \ V \ \pm 5\%, \ V_{SS} = 0, \ T_A = T_L \ to \ T_H), \ unless \ otherwise \ noted)$

Ok	Cumbed.	MC	6802	MC6	8A02	MC6	8B02	Unit
Characteristic	Symbol	Min	Max	Min	Max	Min	Max	Ont
Frequency of Operation	fo	0.1	1.0	0.1	1.5	0.1	2.0	MHz
Crystal Frequency	<b>f</b> XTAL	1.0	4.0	1.0	6.0	1.0	8.0	MHz
External Oscillator Frequency	4xfo	0.4	4.0	0.4	6.0	0.4	8.0	MHz
Crystal Oscillator Start Up Time	t <sub>rc</sub>	100	-	100	—	100	—	ms
Processor Controls (HALT, MR, RE, RESET, IRQ NMI) Processor Control Setup Time Processor Control Rise and Fall Time (Does Not Apply to RESET)	tPCS tPCr, tPCf	200	- 100	140	- 100	110	- 100	ns

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#### **BUS TIMING CHARACTERISTICS**

ldent.			MC	5802	MC6	BA02	MC6	8B02	Unit
Number	Characteristic	Symbol	Min	Max	Min	Max	Min	Max	Unit
1	Cycle Time	t <sub>cyc</sub>	1.0	10	0.667	10	0.5	10	μS
2	Pulse Width, E Low	PWEL	450	5000	280	5000	210	5000	ns
3	Pulse Width, E High	PWEH	450	9500	280	9700	220	9700	ns
4	Clock Rise and Fall Time	t <sub>r</sub> , t <sub>f</sub>	-	25	_	25	_	25	ns
9	Address Hold Time*	<sup>t</sup> AH	20		20	—	20	_	ns
12	Non-Muxed Address Valid Time to E (see Note 4)	tAV1 tAV2	160	270	100	_	50 —	-	ns
17	Read Data Setup Time	tDSR	100	—	70	—	60		ns
18	Read Data Hold Time	<sup>t</sup> DHR	10	-	10	<u> </u>	10	-	ns
19	Write Data Delay Time	tDDW	_	225		170		160	ns
21	Write Data Hold Time*	<sup>t</sup> DHW	30	Ι	20		20		ns
29	Usable Access Time (see Note 4)	tACC	535	-	335	-	235	- 1	ns

FIGURE 2 - BUS TIMING

\*Address and data hold times are periodically tested rather than 100% tested.



#### NOTES:

- 1. Voltage levels shown are VL≤0.4 V, VH≥2.4 V, unless otherwise specified.
- Measurement points shown are 0.8 V and 2.0 V, unless otherwise noted.
  Usable access time is computed by: 12+3+4-17.
- O source access time is computed by: 12+3+4-17.
  If programs are not executed from on-board RAM, TAV1 applies. If programs are to be stored and executed from on-board RAM, TAV2 applies. For normal data storage in the on-board RAM, this extended delay does not apply. Programs cannot be executed from on-board RAM when using A and B parts (MC68A02, MC68B02). On-board RAM can be used for data storage with all parts.
- 5. All electrical and control characteristics are referenced from:  $T_L = 0^{\circ}C$  minimum and  $T_H = 70^{\circ}C$  maximum.

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#### MPU REGISTERS

#### INDEX REGISTER

A general block diagram of the MC6802 is shown in Figure 1. As shown, the number and configuration of the registers are the same as for the MC6800. The  $128 \times 8$ -bit RAM\* has been added to the basic MPU. The first 32 bytes can be retained during powerup and power-down conditions via the RE signal.

The MPU has three 16-bit registers and three 8-bit registers available for use by the programmer (Figure 7).

#### **PROGRAM COUNTER**

The program conter is a two byte (16-bit) register that points to the current program address.

#### STACK POINTER

The stack pointer is a two byte register that contains the address of the next available location in an external pushdown/pop-up stack. This stack is normally a random access read/write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be non-volatile. The index register is a two byte register that is used to store data or a 16-bit memory address for the indexed mode of memory addressing.

#### ACCUMULATORS

The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit (ALU).

## CONDITION CODE REGISTER

The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative (N), Zero (Z), Overflow (V), Carry from bit 7 (C), and Half Carry from bit 3 (H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit (I). The unused bits of the Condition Code Register (b6 and b7) are ones.

Figure 8 shows the order of saving the microprocessor status within the stack.



#### FIGURE 7 - PROGRAMMING MODEL OF THE MICROPROCESSING UNIT

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<sup>\*</sup>If programs are not executed from on-board RAM, TAV1 applies. If programs are to be stored and executed from on-board RAM, TAV2 applies. For normal data storage in the on-board RAM, this extended delay does not apply. Programs cannot be executed from on-board RAM when using A and B parts (MC68A02 and MC68B02). On-board RAM can be used for data storage with all parts.

#### FIGURE 8 - SAVING THE STATUS OF THE MICROPROCESSOR IN THE STACK

SP = Stack Pointer

CC = Condition Codes (Also called the Processor Status Byte)

ACCB = Accumulator B ACCA = Accumulator A

- IXH = Index Register, Higher Order 8 Bits IXL = Index Register, Lower Order 8 Bits
- PCH = Program Counter, Higher Order 8 Bits
- PCL = Program Counter, Lower Order 8 Bits



#### MPU SIGNAL DESCRIPTION

Proper operation of the MPU requires that certain control and timing signals be provided to accomplish specific functions and that other signal lines be monitored to determine the state of the processor. These control and timing signals are similar to those of the MC6800 except that TSC, DBE,  $\phi$ 1,  $\phi$ 2 input, and two unused pins have been eliminated, and the following signal and timing lines have been added:

RAM Enable (RE) Crystal Connections EXTAL and XTAL Memory Ready (MR) VCC Standby

Enable ¢2 Output (E)

The following is a summary of the MPU signals:

#### ADDRESS BUS (A0-A15)

Sixteen pins are used for the address bus. The outputs are capable of driving one standard TTL load and 90 pF. These lines do not have three-state capability.

#### DATA BUS (D0-D7)

Eight pins are used for the data bus. It is bidirectional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130 pF.

Data bus will be in the output mode when the internal RAM is accessed and RE will be high. This prohibits external data entering the MPU. It should be noted that the internal RAM is fully decoded from \$0000 to \$007F. External RAM at \$0000 to \$007F must be disabled when internal RAM is accessed.

#### HALT

When this input is in the low state, all activity in the machine will be halted. This input is level sensitive. In the HALT mode, the machine will stop at the end of an instruc-

tion, bus available will be at a high state, valid memory address will be at a low state. The address bus will display the address of the next instruction.

To ensure single instruction operation, transition of the HALT line must occur tPCS before the rising edge of E and the HALT line must go high for one clock cycle.

HALT should be tied high if not used. This is good engineering design practice in general and necessary to ensure proper operation of the part.

#### READ/WRITE (R/W)

This TTL-compatible output signals the peripherals and memory devices whether the MPU is in a read (high) or write (low) state. The normal standby state of this signal is read (high). When the processor is halted, it will be in the read state. This output is capable of driving one standard TTL load and 90 pF.

#### VALID MEMORY ADDRESS (VMA)

This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90 pF may be directly driven by this active high signal.

BUS AVAILABLE (BA) - The bus available signal will normally be in the low state; when activated, it will go to the high state indicating that the microprocessor has stopped and that the address bus is available (but not in a three-state condition). This will occur if the HALT line is in the low state or the processor is in the WAIT state as a result of the execution of a WAIT instruction. At such time, all three-state output drivers will go to their off-state and other outputs to their normally inactive level. The processor is removed from the

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WAIT state by the occurrence of a maskable (mask bit l = 0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30 pF.

#### INTERRUPT REQUEST (IRQ)

A low level on this input requests that an interrupt sequence be generated within the machine. The processor will wait until it completes the current instruction that is being excuted before it recognizes the request. At that time, if the interrupt mask bit in the condition code register is not set, the machine will begin an interrupt sequence. The index register, program counter, accumulators, and condition code register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit vectoring address which is located in memory locations \$FFF8 and \$FFF9 is loaded which causes the MPU to branch to an interrupt routine in memory.

The HALT line must be in the high state for interrupts to be serviced. Interrupts will be latched internally while HALT is low.

A nominal 3 k $\Omega$  pullup resistor to V<sub>CC</sub> should be used for wire-OR and optimum control of interrupts. IRQ may be tied directly to V<sub>CC</sub> if not used.

#### RESET

This input is used to reset and start the MPU from a power-down condition, resulting from a power failure or an initial start-up of the processor. When this line is low, the MPU is inactive and the information in the registers will be lost. If a high level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execu-

tion of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced high. For the restart, the last two (\$FFFE, \$FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by IRO. Power-up and reset timing and powerdown sequences are shown in Figures 9 and 10, respectively.

RESET, when brought low, must be held low at least three clock cycles. This allows adequate time to respond internally to the reset. This is independent of the  $t_{rc}$  power-up reset that is required.

When RESET is released it *must* go through the low-tohigh threshold without bouncing, oscillating, or otherwise causing an erroneous reset (less than three clock cycles). This may cause improper MPU operation until the next valid reset.

## NON-MASKABLE INTERRUPT (NMI)

A low-going edge on this input requests that a nonmaskable interrupt sequence be generated within the processor. As with the interrupt request signal, the processor will complete the current instruction that is being executed before it recognizes the  $\overline{NMI}$  signal. The interrupt mask bit in the condition code register has no effect on  $\overline{NMI}$ .

The index register, program counter, accumulators, and condition code registers are stored away on the stack. At the end of the cycle, a 16-bit vectoring address which is located in memory locations \$FFFC and \$FFFD is loaded causing the MPU to branch to an interrupt service routine in memory.

A nominal 3 kΩ pullup resistor to VCC should be used for wire-OR and optimum control of interrupts.  $\overline{NMI}$  may be tied

FIGURE 9 - POWER-UP AND RESET TIMING



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directly to  $V_{CC}$  if not used. Inputs  $\overline{IRQ}$  and  $\overline{NM}$  are hardware interrupt lines that are sampled when E is high and will start the interrupt routine on a low E following the completion of an instruction.

Figure 11 is a flowchart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.

#### TABLE 1 - MEMORY MAP FOR INTERRUPT VECTORS

	Vector						
Description							
Restart	\$FFFF	<b>\$FFFE</b>					
Non-Maskable Interrupt	\$FFFD	\$FFFC					
Software Interrupt	\$FFFB	\$FFFA					
Interrupt Request	\$FFF9	\$FFF8					





#### FIGURE 11 - MPU FLOWCHART



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FIGURE 12 - CRYSTAL SPECIFICATIONS



Y1	Cin	Cout
3.58 MHz	27 pF	27 pF
4 MHz	27 pF	27 pF
6 MHz	20 pF	20 pF
8 MHz	18 pF	18 pF

#### Crystal Loading



Nominal Crystal Parameters\*

	3.58 MHz	4.0 MHz	6.0 MHz	8.0 MHz
RS	60 <b>N</b>	50 <b>û</b>	30-50 <b>N</b>	20-40 Ω
CO	3.5 pF	6.5 pF	4-6 pF	4-6 pF
C1	0.015 pF	0.025 pF	0.01-0.02 pF	0.01-0.02 pF
0	>40K	> 30K	> 20K	> 20K

 These are representative AT-cut parallel resonance crystal parameters only. Crystals of other types of cuts may also be used.



Example of Board Design Using the Crystal Oscillator



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#### FIGURE 14 - MEMORY READY SYNCHRONIZATION



#### FIGURE 15 - MR NEGATIVE SETUP TIME REQUIREMENT

#### E Clock Stretch



The E clock will be stretched at end of E high of the cycle during which. MR negative meets the tpcs setup time. The tpcs setup time is referenced to the fall of E. If the tpcs setup time is not met, E will be stretched at the end of the next E-high ½ cycle. E will be stretched in integral multiples of ½ cycles.

Resuming E Clocking



The E clock will resume normal operation at the end of the ½ cycle during which MR assertion meets the tp<sub>CS</sub> setup time. The tp<sub>CS</sub> setup time is referenced to transitions of E were it not stretched. If tp<sub>CS</sub> setup time is not met, E will fall at the second possible transition time after MR is asserted. There is no direct means of determining when the tp<sub>CS</sub> references occur, unless the synchronizing circuit of Figure 14 is used.

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#### RAM ENABLE (RE)

A TTL-compatible RAM enable input controls the onchip RAM of the MC6802. When placed in the high state, the on-chip memory is enabled to respond to the MPU controls. In the low state, RAM is disabled. This pin may also be utilized to disable reading and writing the onchip RAM during a powerdown situation. RAM Enable must be low three cycles before V<sub>CC</sub> goes below 4.75 V during powerdown. RE should be tied to the correct high or low state if not used.

#### EXTAL AND XTAL

These inputs are used for the internal oscillator that may a be crystal controlled. These connections are for a parallel resonant fundamental crystal (see Figure 12). (AT-cut.) A divide-by-four circuit has been added so a 4 MHz crystal may be used in lieu of a 1 MHz crystal for a more cost-effective system. An example of the crystal circuit layout is shown in Figure 13. Pin 39 may be driven externally by a TTL input signal four times the required E clock frequency. Pin 38 is to be grounded.

An RC network is not directly usable as a frequency source on pins 38 and 39. An RC network type TTL or CMOS oscillator will work well as long as the TTL or CMOS output drives the on-chip oscillator.

LC networks are not recommended to be used in place of the crystal.

If an external clock is used, it may not be halted for more than tpW\_bL. The MC6802 is a dynamic part except for the internal RAM, and requires the external clock to retain information.

#### MEMORY READY (MR)

MR is a TTL-compatible input signal controlling the stretching of E. Use of MR requires synchronization with the  $4xf_0$  signal, as shown in Figure 14. When MR is high, E will be in normal operation. When MR is low, E will be stretched integral numbers of half periods, thus allowing interface to slow memories. Memory Ready timing is shown in Figure 15.

MR should be tied high (connected directly to  $V_{CC}$ ) if not used. This is necessary to ensure proper operation of the part. A maximum stretch is  $t_{CVC}$ .

#### ENABLE (E)

This pin supplies the clock for the MPU and the rest of the system. This is a single-phase, TTL-compatible clock. This clock may be conditioned by a memory read signal. This is equivalent to  $\phi 2$  on the MC6800. This output is capable of driving one standard TTL load and 130 pF.

#### VCC STANDBY

This pin supplies the dc voltage to the first 32 bytes of RAM as well as the RAM Enable (RE) control logic. Thus, retention of data in this portion of the RAM on a power-up, power-down, or standby condition is guaranteed. Maximum current drain at VSB maximum is ISBB-

#### MPU INSTRUCTION SET

The instruction set has 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions (Tables 2 through 6). The instruction set is the same as that for the MC6800.

### MPU ADDRESSING MODES

There are seven address modes that can be used by a programmer, with the addressing mode a function of both the type of instruction and the coding within the instruction. A summary of the addressing modes for a particular instruction can be found in Table 7 along with the associated instruction execution time that is given in machine cycles. With a bus frequency of 1 MHz, these times would be microseconds.

#### ACCUMULATOR (ACCX) ADDRESSING

In accumulator only addressing, either accumulator A or accumulator B is specified. These are one-byte instructions.

#### IMMEDIATE ADDRESSING

In immediate addressing, the operand is contained in the second byte of the instruction except LDS and LDX which have the operand in the second and third bytes of the instruction. The MPU addresses this location when it fetches the immediate instruction for execution. These are two- or three-byte instructions.

#### DIRECT ADDRESSING

In direct addressing, the address of the operand is contained in the second byte of the instruction. Direct addressing allows the user to directly address the lowest 256 bytes in the machine, i.e., locations zero through 255. Enhanced execution times are achieved by storing data in these locations. In most configurations, it should be a random-access memory. These are two-byte instructions.

#### EXTENDED ADDRESSING

In extended addressing, the address contained in the second byte of the instruction is used as the higher eight bits of the address of the operand. The third byte of the instruction is used as the lower eight bits of the address for the operand. This is an absolute address in memory. These are three-byte instructions.

#### INDEXED ADDRESSING

In indexed addressing, the address contained in the second byte of the instruction is added to the index register's lowest eight bits in the MPU. The carry is then added to the higher order eight bits of the index register. This result is then used to address memory. The modified address is held in a temporary address register so there is no change to the index register. These are two-byte instructions.

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#### IMPLIED ADDRESSING

In the implied addressing mode, the instruction gives the address (i.e., stack pointer, index register, etc.). These are one-byte instructions.

#### RELATIVE ADDRESSING

In relative addressing, the address contained in the second

byte of the instruction is added to the program counter's lowest eight bits plus two. The carry or borrow is then added to the high eight bits. This allows the user to address data within a range of -125 to +129 bytes of the present instruction. These are two-byte instructions.

#### TABLE 2 - MICROPROCESSOR INSTRUCTION SET - ALPHABETIC SEQUENCE

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			IMMED			MMCO			MMED			REC		DRES	DEX			TNC	<u>,</u> т	1844	LIE	n	(All register labels	5 4	i Ti	1	1	Т
		0P	AME		0.0	HEL		0.0	UEA	=		-	=	DP		z	-											
PERATIONS	MNEMONIC			_	_		_		_	- +		4	3			-	A + M - A	÷t	•	:		:						
dd	ADDA	38 CB	2 2	2	98 08	3 3	2	AB EB	5	2		4	3				8 • M • B											
Add Acmitrs	ADDB ABA	LB	2	2	06	2	<i>`</i>	6.0	2	'			1	1 B	2	1	A+B-A		•	1								
Add with Carry	ADCA	89	2	2	99	3	2	A9	5	2	89	4	3				A + M + C - A	: 1			: :							
	ADCB	C9	2	2	D9	3	2	E9	5	2	F9	4	3				B + M + C - B	: 1				:						
And	ANDA	84	2	2	94	3	2	A4	5	2	B4	4	3									R						
	ANDB	C4	2	2	D4	3	z	E4	5	2	F4	4	3				8 · M · B		- I			R						
Bit Test	BITA	85	2	2	95	3	2	A5	5	2	85	4	3				A · M					· .						
	BITB	C5	2	2	D5	3	2	65	5	2	۶5	4	3 :				B · M					R						
Clear	CLA							6F	1	2	7 F	6	3	4F	2	1	00 - M 00 - A					R						
	CLRA	1			i									41 55	2	1	00 - 8					R						
_	CLRB	81			91	3	2	A1	5	2	B1	4	3	37	ł		A M		•									
Compare	CMPA CMPB	81	2	2	91 D1	3	2	EI	5 5	2	E F I	4	3				B M		•	1		:						
Compare Acmirs	CBA	C.	4	ć		2	-			-			2	11	2	;	AB		•	:	:	:						
Complement, 1's	COM							63	7	2	73	6	3		-		MA - M	•	•			R						
compression, 1 a	COMA													43	2	1	Ā · A		•	:1		R						
	COMB													53	2	1	B - B		•	: [		Rİ						
Complement, 2's	NEG	1						60	7	2	70	6	3				00 M · M			:		D						
(Negate)	NEGA	1									l			40	2	1	A - A 00			:		D						
-	NEGB	1												50	2	1			•			D						
Decimal Adjust, A	DAA	L			1									19	5	1		•	•	:1	:	:						
		1															into BCD Format			.	. ا	~						
Decrement	DEC	1			1			6A	7	2	7A	6	3	l			M 1 M		:	:	1	90						
	DECA													4A	2	1	Δ 1 - Δ		:	1	÷k	3						
	DECB													5A	2	1	B 1 · B					R						
Exclusive C.R	EORA	88	2	2	98	3	2	A8	5	2	68	4	3				A⊕M ·A					A						
	EORB	C8	2	2	08	3	2	68	5	2	F8	4	3				B⊕M -B M • 1 ·M			:		ŝ						
Increment	INC	1						6C	1	2	70	6	3	40	2	,						5)						
	INCA													4U 5C	2	1				1		5						
	INCB	1		2	96	3	2	A6	5	2	86	4	3	30	2		M A			1		R						
Load Acmitr	LDAA	86 C6	2	2	06	3	2	66	5	ź	F6	4	3				M · B			1		R						
	LDAB			2	06   9A	3	ź	AA	5	2	I BA	4	3				A + M - A		•			R						
Or, Inclusive	ORAA	A8	2	2	DA		2	EA	5	2	FA	4	3	ł			B + M + B		•	E.		R						
	ORAB PSHA	L CA	2	2	104	2	2	1	5	•	1.2			36	4	1			•	•		•						
Push Data	PSHB													37	4	1		•	•	•	•	•						
Pult Data	PULA													32	4	1		•	•	•	•	•						
run pata	PULB							1						33	4	1	SP+1-SP_MSP-8	•	٠	•	•	•						
Rolate Leli	ROL							69	1	2	79	6	3				M)	•	٠	:	: }	¢						
Holdre cert	ROLA													49	2	1		•	٠	:		©						
	ROLB							ł						59	2	1	1 B C b7 - b0	•	•	1:		G						
Rotate Right	ROR							66	7	2	76	6	3				M)	•	•	E.		٢						
	RORA	1												46	2	1		•	•	:		Ś						
	RORB													56	2	1	1 1 2 3	•	٠	÷		Q						
Shift Left, Arithmetic	ASL							68	7	2	78	6	3				M	•	•	1		Q						
	ASLA	1						1						48	2	1			•	÷		6						
	ASLB	1			1			1.						58	2	1		•	•	E		6						
Shift Right, Arithmetic	ASR	1			1			67	7	2	n	Б	3				. M		:			Ć						
	ASRA	1			1			1						41	2	1			:			6						
	ASRB				1							~		57	2	1			:	Å		e e						
Shift Right, Logic	LSR	1			1			64	1	2	74	6	3	44			, M			A		6						
	LSRA				1						1				2	1				R	1	6						
	LSAB				1			<u>م</u>			BZ	ć	3	54	2		A - M					R						
Store Acmitr	STAA				97		2		6 6	2		5	3				A · M B · M			E	:	R						
	STAB									2		4	3				B · № A M·A			Ð	:	1						
Subtract	SUBA	8								2		4	3				B M · B			÷	1	E						
	SUBB	C	5 2	1	DC	J 3	- 4	1 50	2	2	10	4	3	10	2	,	1 A B · A					13						
Subtract Acmitrs.	SBA SBCA	8	2 2	. :	92	2 3	2	A	5	2	82	4	3		4				١.	E	1	÷						
Subir with Carry		6								2			3				B M C ·B			E		:						
	58CB TAB	L C	~ ~		10.	4 3	4	1 54	3	4	112	4	-	16	2		1 A -B			E	÷	R						
Transfer Acmitrs	TBA													17			1 B A				l÷.	R						
T	1BA TST							60	7	2	2 70	6	1		-		M - 00				11	R						
Test. Zero or Minus	TSTA							1 50		ŕ				40	2		1 A - 00	•			:	R						
	TSTR							1						50			1 8 00			H	÷							
	1218							1			1			1.00				1.	+	IN	+	∔						

## TABLE 3 - ACCUMULATOR AND MEMORY INSTRUCTIONS

#### LEGEND:

#### OP Operation Code (Hexadecimal).

- Operation Code (newadectin)
  Number of MPU Cycles,
  Number of Program Bytes,
  Arithmetic Plus,
  Arithmetic Minus,
- Boolean AND.

Msp Contents of memory location pointed to be Stack Pointer

Note - Accumulator addressing mode instructions are included in the column for IMPLIED addressing

CONDITION CODE SYMBOLS

- н Half carry from bit 3,
- interrupt mask
- N Negative (sign bit) Z Zero (byte) V Overflow, 2's complement C Carry from bit 7
- R Reset Always S Set Always
  - Test and set if true cleared otherwise Not Alfected
- ٠

## MOTOROLA MICROPROCESSOR DATA

Boolean Inclusive OR.
 Boolean Exclusive OR.

Complement of M Transfer Into.

0 Bit = Zero. 00 Byte : Zera.

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## TABLE 4 - INDEX REGISTER AND STACK MANIPULATION INSTRUCTIONS

																		CO	ND	. cc	) O E	R	EG.
		H	MME	D	D	IRE	ст	1	NDE	x	E	XTR	D	IN	#Pill	ED	]	5	4	3	2	1	0
POINTER OPERATIONS	MNEMONIC	OP	-	=	OP	-	=	OP	-	=	OP	~	=	OP	-	=	BOOLEAN/ARITHMETIC OPERATION	H	<u> </u>			۷	-
Compare Index Reg	CPX	8C	3	3	90	4	2	AC	6	2	ec	5	3			1	XH - M, XL - (M + 1)	٠	•	0	:1	۲	•
Decrement Index Reg	DEX													09	4	1	X – 1 – X	•	٠	٠	1:1	•	•
Decrement Stack Pntr	DES		1								1		1	34	4	1	SP 1 - SP	•	•	٠	٠	•	•
Increment Index Reg	INX				i i									08	4	1	X + 1 · X	•	٠	٠	1	٠	•
Increment Stack Potr	INS											ĺ		31	4	1	SP + 1 · SP	•	•	٠	<b> •</b> '	•	•
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	6	2	FE	5	3		1		M - XH, (M + 1) - XL			9		R	•
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	6	2	BE	5	3		1	-	M - SPH. (M + 1) - SPL			9		R	•
Store Index Reg	STX				OF	5	2	EF	7	2	FF	6	3		i	1	XH + M, XL + (M + 1)			9		R	•
Store Stack Pntr	STS		1	1	9F	5	2	AF	1	2	BF	6	3				SPH - M. SPL - (M + 1)	•	•	۹	1:	R	•
and x Reg + Stack Potr	TXS		1				1	1			i –	ł –		35	4	11	X 1 · SP	•	•	•	•	•	•
Stack Potr - Indx Reg	TSX											ί.		30	4	1	SP+1 · X	•	•	•	•	٠	•

#### TABLE 5 - JUMP AND BRANCH INSTRUCTIONS

COND. CODE REG.

										-	<u> </u>			5 4 3		Τ.
		RE	LAT	VE		NDE	x	E	XTN	D	IN	PLI	D	5 4 3	2 1	
OPERATIONS	MNEMONIC	OP	~	=	OP	1	#	OP	~	=	OP	~	=	BRANCH TEST H I N	z v	C
Branch Always	BRA	20	4	2								I		None • •	•   •	•
Branch If Carry Clear	BCC	24	4	2										C = 0 • • •	• •	•
Branch If Carry Set	BCS	25	4	2										C = 1 • • •	• •	•
Branch If = Zero	BEQ	27	4	2							-			Z = 1	• •	•
Branch II ≥ Zero	BGE	20	4	2						1	ĺ –	1	1	N ⊕ V = 0	• •	•
Branch It > Zero	BGT	2E	4	2							[			Z + (N ⊕ V) = 0 • • •	• •	• •
Branch If Higher	вні	22	4	2						ł				C+Z=0	• •	•
Branch If ≤ Zero	BLE	2F	4	2				1						Z + (N ⊕ V) = 1 • ; • ; • ; •	• •	•
Branch If Lower Or Same	BLS	23	4	2						ļ			1	C + Z = 1	• •	•
Branch II < Zero	BLT	20	4	2						ļ				N ⊕ V = 1 • • •	• •	• •
Branch If Minus	BMI	28	4	2			ļ							N=1 • •	• •	•
Branch If Not Equal Zero	BNE	26	4	2						1			ł.	Z = 0 • • •		•
Branch II Overflow Clear	BVC	28	4	2										V=0 • • •		•
Branch If Overflow Set	BVS	29	4	2			Ì					1		V=1 • • •		•
Branch If Plus	BPL	24	4	2				i i						N = 0 • • •		
Branch To Subroutine	BSB	80	8	2	i i		1					1	1	_   •   •   •	• •	•
Jump	IMP	1 **	-	1	6E	4	2	76	3	3				See Special Operations	• •	•
Jump To Subroutine	JSR				AD	8	2	BD	9	3			1	(Figure 16)		•
No Operation	NOP	1					ĺ				01	2	1	Advances Prog. Cntr. Univ • • •	• •	•
Return From Interrupt	RTI							1			38	10	1	(ii	) <u> </u>	
Return From Subroutine	RTS		1								39	5	11	)  • • •]		• į ●
Software Interrupt	SWI	1			t l		1				3F	12	1	See Special Operations	• •	•
Wait for Interrupt	WAI							l l	1		36	9	1	(Figure 16) • (1) •	• •	•

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#### FIGURE 16 - SPECIAL OPERATIONS



## TABLE 6 - CONDITION CODE REGISTER MANIPULATION INSTRUCTIONS

							00.	0 0		neu.	
		IN	PLI	D		5	4	3	2	1	0
OPERATIONS	MNEMONIC	OP	~	Ξ	BOOLEAN OPERATION	н	1	N	z	٧	C
Clear Carry	CLC	00	2	1	0 · C	٠	•	•	•	•	, b
Clear Interrupt Mask	CLI	0E	2	1	0 • 1	•	R	٠	٠	٠	•
Clear Overflow	CLV	0A	2	1	0 · V	•	•	•	•	R	•
Set Carry	SEC	0D	2	1	1 · C	•	•	٠	•	٠	5
Set Interrupt Mask	SE	۵f	2	1	1.+1	•	S	•	٠	•	•
Set Overflow	SEV	0B	2	1	1 · V	•	•	۰.	•	١S	•
Acmitr A + CCR	ΤΑΡ	06	2	1	A -CCR	I —		-3	12 –		
CCR -+ Acmitr A	TPA	07	2	1	CCR · A	•	•	÷.	•	•	1.1

CONDITION CODE REGISTER NOTES: (Bit set if test is true and cleared otherwise)

(Bit V) Test Result = 10000000?

Test Result # 00000000?

(Not cleared if previously set ) Test: Operand = 10000000 prior to execution?

(Bit V) Test Operand = 01111111 prior to execution?

(Bit V) Test: Set equal to result of N⊕C after shift has occurred

Test. Decimal value of most significant BCD Character greater than nine?

1

3 (Brt C)

4

6

2 (Bit C)

(Bet V)

7 (Bit N) Test Sign bit of most significant (MS) byte = 17

8

10

(Bit V) Test 2's complement overflow from subtraction of MS bytes?

- 9 (Bit N) Test Result less than zero? (Bit 15 1)
  - (All) Load Condition Code Register from Stack. (See Special Operations)
- 11 (Bit I) Set when interrupt occurs If previously set, a Non Maskable
  - Interrupt is required to exit the wait state
- 12 (All) Set according to the contents of Accumulator A

## MOTOROLA MICROPROCESSOR DATA

	(Duat Operand)	ACCX	hmmediate	Direct	Extended	Indexed	Implied	Relative		(Dual Operand)	ACCX	Immediate	Direct	Extended	Indexed	Implied
ABA		٠	•	٠	٠	٠	2	•	INC		2	•	٠	6	7	٠
ADC	x	٠	2	3	4	5	٠	•	INS		•	٠	٠	•	•	4
ADD	×	•	2	3	4	5	•	٠	INX		•	•	•	•	•	4
AND ASL	x		2	3	4	5	٠	•	JMP		•	•	•	3 9	4	•
ASL		2	•	•	6	7	•	•	JSR		•		3	9 4	8 5	•
BCC		2	•	•	6	7	•	•	LDA	×	٠	2 3	3	4	5	•
BCS		•	•	•	•	•	•	4	LDS LDX		•	3	4	5	6	•
BEA		•	•	•	•	•	•	4	LDA		•			6	7	•
BGE		•	:	•	:	•	•	4	NEG		2 2	:	:	6	7	:
BGT					:		•	4	NOP		-			•		2
вні			-	:	:			4	ORA	×		2	3	4	5	•
BIT	x		2	3	4	5		-	PSH	^			•			4
BLE	<u>^</u>						-	4	PUL							4
BLS								4	ROL		2			6	7	
BLT								4	ROR		2			6	7	•
BMI			•	•		•		4	BTI				•	•		10
BNE					•			4	RTS				•			5
BPL			•			•		4	SBA						•	2
BRA		٠						4	SBC	×		2	3	4	5	•
BSR		•	٠	•	•	•	•	8	SEC		٠			•	•	2
BVC		•	•	•	•	•	٠	4	SEI		•	•	•	•	•	2
BVS		٠	٠	•	٠	٠	•	4	SEV		•	•	٠	٠	•	2
CBA		٠	٠	٠	٠	٠	2	٠	STA	×	٠	•	4	5	6	•
CLC		٠	•	•	٠	٠	2	٠	STS		٠	•	5	6	7	•
CLI		٠	•	•	•	•	2	٠	STX		٠	•	5	6	7	•
CLR		2	•	•	6	7	•	٠	SUB	×	٠	2	3	4	5	٠
CLV		٠	•	•	•	•	2	٠	SWI		٠	٠	٠	٠	٠	12
CMP	×	•	2	3	4	5	٠	•	TAB		٠	٠	٠	٠	٠	2
COM		2	•	•	6	7	٠	•	TAP		٠	٠	•	•	٠	2
CPX		٠	з	4	5	6	•	•	TBA		•	٠	٠	•	٠	2
DAA DEC			•	•	•		2	•	TPA		•	•	•	•	•	2
DEC		2	•	•	6	7	•	•	TST TSX		2	•	•	6	7	•
DES		•	•	•	•	•	4	•	TSX		•	•	•	•	•	4
EOR		•	2	3	4	5	4	•	WAI		•	•	•	•	•	9
EOH	x	•	2	3	4	5	•	•	WAI		•	•	•	•	•	э

# TABLE 7 - INSTRUCTION ADDRESSING MODES AND ASSOCIATED EXECUTION TIMES (Times in Machine Cycle)

.

NOTE Interrupt time is 12 cycles from the end of the instruction being executed, except following a WAL instruction. Then it is 4 cycles

## MOTOROLA MICROPROCESSOR DATA

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## SUMMARY OF CYCLE-BY-CYCLE OPERATION

Table 8 provides a detailed description of the information present on the address bus, data bus, valid memory address line (VMA), and the read/write line (R/W) during each cycle for each instruction.

This information is useful in comparing actual with expected results during debug of both software and hardware

as the control program is executed. The information is categorized in groups according to addressing modes and number of cycles per instruction. (In general, instructions with the same addressing mode and number of cycles execute in the same manner; exceptions are indicated in the table.)

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
IMMEDIATE		<b>L</b>	·			
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA AND ORA	2	2	1	Op Code Address + 1	1	Operand Data
BIT SBC	2					
CMP SUB					_	
CPX LDS		1	1	Op Code Address	1	Op Code
LDX	3	2	1	Op Code Address + 1	1	Operand Data (High Order Byte)
		3	1	Op Code Address + 2	1	Operand Data (Low Order Byte)
DIRECT		<b>.</b>	1			
ADC EOR ADD LDA		1	1	Op Code Address	1	Op Code
AND ORA	3	2	1	Op Code Address + 1	1	Address of Operand
BIT SBC CMP SUB		3	1	Address of Operand	1	Operand Data
СРХ	+	1	1	Op Code Address	1	Op Code
LDS	4	2	1	Op Code Address + 1	1	Address of Operand
LDX	1	3	1	Address of Operand	1	Operand Data (High Order Byte)
		4	1	Operand Address + 1	1	Operand Data (Low Order Byte)
STA	-	1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Destination Address
		3	0	Destination Address	1	Irrelevant Data (Note 1)
		4	1	Destination Address	0	Data from Accumulator
STS		1	1	Op Code Address	1	Op Code
STX		2	1	Op Code Address + 1	1	Address of Operand
	5	3	0	Address of Operand	1	Irrelevant Data (Note 1)
		4	1	Address of Operand	0	Register Data (High Order Byte)
		5	1	Address of Operand + 1	0	Register Data (Low Order Byte)
INDEXED	- I	<u> </u>				•
JMP		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Offset
	1	3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA AND ORA		2	1	Op Code Address + 1	1	Offset
BIT SBC	5	3	0	Index Register	1	Irrelevant Data (Note 1)
CMP SUB		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Operand Data
CPX	+	1	1	Op Code Address	1	Op Code
LDS		2	1	Op Code Address + 1	1	Offset
LDX	6	3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Operand Data (High Order Byte)
	1	6	1	Index Register Plus Offset + 1	1	Operand Data (Low Order Byte)

#### TABLE 8 - OPERATIONS SUMMARY

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	TABLE 8 - OPERATIONS SUMMARY (CONTINUED)								
Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/Ŵ Line	Data Bus			
INDEXED (Continued)	r					<u> </u>			
STA		1		Op Code Address	1	Op Code			
		2	1	Op Code Address + 1	1	Offset			
	6	3	0	Index Register	1	Irrelevant Data (Note 1)			
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)			
		5	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)			
		6	1	Index Register Plus Offset	0	Operand Data			
ASL LSR ASR NEG	-	1	1	Op Code Address	1	Op Code			
CLR ROL		2	1	Op Code Address + 1	1	Offset			
COM ROR DEC TST	7	3	0	Index Register	1	Irrelevant Data (Note 1)			
INC		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)			
		5	1	Index Register Plus Offset	1	Current Operand Data			
		6	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)			
		7	1/0 (Note 3)	Index Register Plus Offset	0	New Operand Data (Note 3)			
STS		1	1	Op Code Address	1	Op Code			
STX		2	1	Op Code Address + 1	1	Offset			
	7	3	0	Index Register	1	Irrelevant Data (Note 1)			
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)			
		5	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)			
		6	1	Index Register Plus Offset	0	Operand Data (High Order Byte)			
		7	1	Index Register Plus Offset + 1	0	Operand Data (Low Order Byte)			
JSR	1	1	1	Op Code Address	1	Op Code			
		2	1	Op Code Address + 1	1	Offset			
		3	0	Index Register	1	frrelevant Data (Note 1)			
	8	4	1	Stack Pointer	0	Return Address (Low Order Byte)			
	°	5	1	Stack Pointer 1	0	Return Address (High Order Byte)			
		6	0	Stack Pointer – 2	1	Irrelevant Data (Note 1)			
		7	0	Index Register	1	Irrelevant Data (Note 1)			
		8	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)			
EXTENDED	4	1 -	1 -						
JMP		1	1	Op Code Address	1	Op Code			
	3	2	1	Op Code Address + 1	1	Jump Address (High Order Byte)			
		3	1	Op Code Address + 2	1	Jump Address (Low Order Byte)			
ADC EOR	1	1	1	Op Code Address	1	Op Code			
ADD LDA	4	2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)			
AND ORA BIT SBC	4	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)			
CMP SUB		4	1	Address of Operand	1	Operand Data			
CPX	1	1	1	Op Code Address	1	Op Code			
LDS		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)			
LDX	5	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)			
		4	1	Address of Operand	1	Operand Data (High Order Byte)			
		5	1	Address of Operand + 1	1	Operand Data (Low Order Byte)			
STA A	1	1	1	Op Code Address	1	Op Code			
STA B		2	1	Op Code Address + 1	1	Destination Address (High Order Byte)			
	5	3		Op Code Address + 2	l i	Destination Address (Low Order Byte)			
	Ĭ	4	o	Operand Destination Address		Irrelevant Data (Note 1)			
		5		Operand Destination Address	o	Data from Accumulator			
ASL LSR	+	1	+	Op Code Address	1	Op Code			
ASR NEG	1	2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)			
CLR ROL COM ROR		3		Op Code Address + 1		Address of Operand (Low Order Byte)			
DEC TST	6	4		Address of Operand		Current Operand Data			
INC	1	4							
		6	1/0 (Note	Address of Operand Address of Operand	0	Irrelevant Data (Note 1) New Operand Data (Note 3)			

TABLE 8 - OPERATIONS SUMM.	ARY (CONTINUED)
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TABLE 8	OPERATIONS	SUMMARY	(CONTINUED)
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Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
EXTENDED (Continued)						
STS STX	1	1	1	Op Code Address	1	Op Code
317		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)
	6	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
	-	4	0	Address of Operand	1	Irrelevant Data (Note 1)
		5	1	Address of Operand	0	Operand Data (High Order Byte)
		6	1	Address of Operand + 1	0	Operand Data (Low Order Byte)
JSR	1	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Subroutine (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)
		4	1	Subroutine Starting Address	1	Op Code of Next Instruction
	9	5	1	Stack Pointer	0	Return Address (Low Order Byte)
	1	6	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		7	0	Stack Pointer – 2	1	Irrelevant Data (Note 1)
		8	0	Op Code Address + 2	1	Irrelevant Data (Note 1)
		9	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte
INHERENT	<b>-</b>				- ···	L
ABA DAA SEC		1	1	Op Code Address	1	Op Code
ASL DEC SEI	2	2	1	Op Code Address + 1	1	Op Code of Next Instruction
ASR INC SEV CBA LSR TAB		-				
CLC NEG TAP						
CLI NOP TBA CLR ROL TPA	l.					
CLV ROR TST						
COM SBA						
DES DEX		1	1	Op Code Address	1	Op Code
INS	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
INX		3	0	Previous Register Contents	1	Irrelevant Data (Note 1)
	1	4	0	New Register Contents	1	Irrelevant Data (Note 1)
PSH		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	1	Stack Pointer	0	Accumulator Data
		4	0	Stack Pointer – 1	1	Accumulator Data
PUL		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
	1	3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Operand Data from Stack
TSX	1	1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
	1	3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	0	New Index Register	1	Irrelevant Data (Note 1)
TXS	†	1 1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
	4	3	0	Index Register	1	Irrelevant Data
		4	0	New Stack Pointer	1	Irrelevant Data
RTS	+	1 1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1		Irrelevant Data (Note 2)
	5	3	0	Stack Pointer		Irrelevant Data (Note 1)
	5	4	1	Stack Pointer Stack Pointer + 1	1	Address of Next Instruction (High
	1	5	1	Stack Pointer + 2	1	Order Byte) Address of Next Instruction (Low

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Address Mode		Cycle	VMA		R/W	
and Instructions	Cycles	#	Line	Address Bus	Line	Data Bus
INHERENT (Continued)				Op Code Address	1	Op Code
WAI	1		1	Op Code Address + 1		Op Code of Next Instruction
		2			0	Return Address (Low Order Byte)
		3	1	Stack Pointer	o	Return Address (High Order Byte)
		4	1	Stack Pointer 1	0	Index Register (Low Order Byte)
	9	5	1	Stack Pointer – 2	0	Index Register (High Order Byte)
		6	1	Stack Pointer – 3	0	Contents of Accumulator A
		7	1	Stack Pointer - 4		Contents of Accumulator B
		8	1	Stack Pointer - 5		Contents of Cond. Code Register
	+	9	1	Stack Pointer – 6	<u>'</u>	Op Code
RTI		1	1	Op Code Address		
		2	1	Op Code Address + 1		Irrelevant Data (Note 2)
		3	0	Stack Pointer		Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Contents of Cond. Code Register from Stack
	10	5	1	Stack Pointer + 2	1	Contents of Accumulator B from Stack
	1	6	1	Stack Pointer + 3	1	Contents of Accumulator A from Stack
		7	1	Stack Pointer + 4	1	Index Register from Stack (High Order Byte)
		8	1	Stack Pointer + 5	1	Index Register from Stack (Low Order Byte)
		9	1	Stack Pointer + 6	1	Next Instruction Address from Stack (High Order Byte)
		10	1	Stack Pointer + 7	1	Next Instruction Address from Stack (Low Order Byte)
SWI		1	1	Op Code Address	1	Op Code
3441		2	1	Op Code Address + 1	1	Irrelevant Data (Note 1)
	1	3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		5		Stack Pointer – 2	0	Index Register (Low Order Byte)
		6		Stack Pointer - 3	0	Index Register (High Order Byte)
	12	7		Stack Pointer – 4	0	Contents of Accumulator A
		8		Stack Pointer - 5	0	Contents of Accumulator B
		9		Stack Pointer – 6	0	Contents of Cond. Code Register
		10	0	Stack Pointer - 7	1	Irrelevant Data (Note 1)
		11	1	Vector Address FFFA (Hex)	1	Address of Subroutine (High Order Byte)
		12	1	Vector Address FFFB (Hex)	1	Address of Subroutine (Low Order Byte)
RELATIVE	1	.l	L	<u> </u>		
BCC BHI BNE		1		Op Code Address	1	Op Code
BCS BLE BPL		2		Op Code Address + 1	1	Branch Offset
BEQ BLS BRA	4	3		Op Code Address + 2		Irrelevant Data (Note 1)
BGE BLT BVC BGT BMI BVS		4	0	Branch Address		Irrelevant Data (Note 1)
	+	4		Op Code Address	1	Op Code
BSR		2		Op Code Address + 1		Branch Offset
		3	0	Return Address of Main Program		Irrelevant Data (Note 1)
		1 -	-	Stack Pointer	0	Return Address (Low Order Byte)
	8	4	1		0	Return Address (Low Order Byte)
		5	1	Stack Pointer – 1	-	Freievant Data (Note 1)
	]	6	0	Stack Pointer - 2	1	
	1	7	0	Return Address of Main Program	1	Irrelevant Data (Note 1)
	1	8	0	Subroutine Address (Note 4)	1	Irrelevant Data (Note 1)

#### TABLE 8 - OPERATIONS SUMMARY (CONCLUDED)

NOTES:

1. If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high-impedance three-state condition. Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.

2. Data is ignored by the MPU.

For TST, VMA=0 and Operand data does not change.
 MS Byte of Address Bus=MS Byte of Address of BSR instruction and LS Byte of Address Bus=LS Byte of Sub-Routine Address

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## **MECHANICAL DATA AND ORDERING INFORMATION**

## **ORDERING INFORMATION**

Package Type	Frequency MHz	Temperature	Order Number
Plastic	1.0	0°C to 70°C	MC6802P
P Suffix	1.0	-40°C to +85°C	MC6802CP
	1.5	0°C to 70°C	MC68A02P
	1.5	- 40°C to + 85°C	MC68A02CP
	2.0	0°C to 70°C	MC68B02P
Cerdip	1.0	0°C to 70°C	MC6802S
S Suffix	1.0	-40°C to +85°C	MC6802CS
	1.5	0°C to 70°C	MC68A02S
	1.5	- 40°C to + 85°C	MC68A02CS
	2.0	0°C to 70°C	MC68B02S

## **PIN ASSIGNMENT**

		<b>_</b>
VSS		40 D RESET
HALT	<b>C</b> 2	39 DEXTAL
MR	¢ 3	38 🖡 XTAL
IRQ	<b>q</b> 4	37 🕽 E
VMA	<b>d</b> 5	36 🖡 RE
NMI	<b>d</b> 6	35 D V <sub>CC</sub> Standby
BA	<b>d</b> 7	34 🕽 R/W
Vcc	C 8	33 <b>D</b> D0
A0	e þ	32 D1
A1	<b>[</b> 10	31 🗗 D2
A2	<b>C</b> 11	30 🗗 D3
A3	<b>[</b> 12	29 🕽 D4
A4	<b>[</b> 13	28 🕽 D5
A5	<b>D</b> 14	27 🗖 D6
A6	<b>[</b> 15	26 D7
A7	<b>C</b> 16	25 🗖 A15
A8	<b>C</b> 17	24 🗋 A14
A9	<b>D</b> 18	23 🗍 A13
A10	<b>[</b> 19	22 🗍 A12
A11	<b>1</b> 20	21 🕽 V <sub>SS</sub>

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